

DECLARATION OF INVENTOR FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: PACKAGES FOR SEMICONDUCTOR DIE, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued therefrom.

* * * * *

Full Name of Sole or first Inventor: Todd O. Bolken

Inventor's Signature

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Bolken et al.
Title: PACKAGES FOR
SEMICONDUCTOR DIE
Express Mail No. EV 339208044 US
Mailed: December 9, 2003
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substitution to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

The Assignee certifies that the above-identified Assignment has been reviewed and to the best of Assignee's knowledge and belief, title is in the Assignee, and a copy of the Assignment is submitted herewith.

Please direct all correspondence regarding this application to:

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MICRON TECHNOLOGY, INC.

Date: Nov 21, 1999

By: 
Name: Michael L. Lynch, Esq.
Title: Chief Patent Counsel

Attachment: Copy of Assignment; Copy of Board of Directors' Resolution